

Abstract

Provided are an amorphous silica powder having extremely high insulation reliability and capable of preparing a semiconductor encapsulant having high moldability, and a resin composition containing the same. The amorphous silica powder has an average particle size of 3 μm or more and 50 μm or less, wherein the percent retention of 250 μm or more by dry sieving is 5.0% by mass or less, and the number of magnetizable particles having a size of 45 μm or more measured by a specific method is zero.